

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT4307519

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	SECURITY INTEREST

**CONVEYING PARTY DATA**

Name	Execution Date
STRASBAUGH AND R.H. STRASBAUGH	11/13/2015

**RECEIVING PARTY DATA**

<b>Name:</b>	BFI BUSINESS FINANCE DBA CAPITALSOURCE BUSINESS FINANCE GROUP
<b>Street Address:</b>	851 E. HAMILTON AVENUE
<b>Internal Address:</b>	#200
<b>City:</b>	CAMPBELL
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95008

**PROPERTY NUMBERS Total: 88**

Property Type	Number
Patent Number:	6045716
Patent Number:	6495463
Patent Number:	6379235
Patent Number:	6361647
Patent Number:	6346036
Patent Number:	6602121
Patent Number:	6337133
Patent Number:	6837133
Patent Number:	6227956
Patent Number:	6527621
Patent Number:	6855030
Patent Number:	6514121
Patent Number:	6629874
Patent Number:	6976901
Patent Number:	6514129
Patent Number:	6520843
Patent Number:	6464574
Patent Number:	6511368
Patent Number:	6551179

**PATENT**

<b>Property Type</b>	<b>Number</b>
Patent Number:	6692339
Patent Number:	6547651
Patent Number:	6945856
Patent Number:	8133093
Patent Number:	6183341
Patent Number:	6595829
Patent Number:	6485354
Patent Number:	6739945
Patent Number:	6696005
Patent Number:	6743722
Patent Number:	6726528
Patent Number:	6884150
Patent Number:	6885206
Patent Number:	6638389
Patent Number:	6866564
Patent Number:	6695681
Patent Number:	7156946
Patent Number:	7008309
Patent Number:	6878037
Patent Number:	6869348
Patent Number:	7059942
Patent Number:	7235154
Patent Number:	7052366
Patent Number:	7063605
Patent Number:	7160808
Patent Number:	6986701
Patent Number:	7040955
Patent Number:	7033252
Patent Number:	5964646
Patent Number:	6254155
Patent Number:	7063604
Patent Number:	7551979
Patent Number:	7083497
Patent Number:	7467990
Patent Number:	7131892
Patent Number:	7195541
Patent Number:	7238083
Patent Number:	7549909

Property Type	Number
Patent Number:	7959496
Patent Number:	8182312
Patent Number:	7918712
Patent Number:	9082713
Patent Number:	7018268
Patent Number:	6921719
Patent Number:	7118446
Patent Number:	7249992
Patent Number:	7458878
Patent Number:	8968052
Patent Number:	8052504
Patent Number:	6450860
Patent Number:	8915771
Patent Number:	8740673
Patent Number:	8520222
Application Number:	12806518
Application Number:	13573148
Application Number:	11393041
Application Number:	14295013
Application Number:	13243808
Application Number:	14042591
Application Number:	13740101
Application Number:	14042600
Application Number:	14525115
Application Number:	13656514
Application Number:	11369700
Application Number:	10452411
Application Number:	10717032
Application Number:	10145332
Application Number:	10315746
Application Number:	10259536

**CORRESPONDENCE DATA**

**Fax Number:**

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

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**PATENT**

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<b>Address Line 4:</b>	TORRANCE, CALIFORNIA 90503

<b>NAME OF SUBMITTER:</b>	IRVING KESCHNER
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<b>SIGNATURE:</b>	/Irving Keschner/
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<b>DATE SIGNED:</b>	03/07/2017
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**Total Attachments: 7**

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## FORECLOSURE SALE AGREEMENT

This FORECLOSURE SALE AGREEMENT (this "Agreement") is made and entered into as of the 8<sup>th</sup> day of November, 2016, by and between CapitalSource Business Finance Group, a dba of BFI Business Finance ("Seller"), and Revasum, Inc., a Delaware corporation ("Purchaser"). Capitalized terms used but not defined in this Agreement shall have the respective meanings set forth in Annex A hereto.

### RECITALS

WHEREAS, Seller, on the one hand, and Strasbaugh and R.H. Strasbaugh (collectively, "Debtor"), on the other hand, are parties to that certain Loan and Security Agreement (Accounts Receivable and Inventory Line of Credit), dated as of November 13, 2015 (such agreement, as amended, supplemented or modified, together with all documents, instruments and agreements related thereto, may be collectively referred to herein as the "Debtor Loan Documents"); and

WHEREAS, in order to secure Debtor's prompt payment and performance of its obligations under the Debtor Loan Documents, Debtor granted to Seller a security interest in and lien upon the assets of Debtor described in Exhibit A attached hereto (the "Transferred Assets"); and

WHEREAS, copies of the two (2) UCC-1 Financing Statements filed by Seller with respect to the Transferred Assets, are attached collectively hereto as Exhibit B; and

WHEREAS, Seller and Purchaser have entered into a Non-Disclosure Agreement, with an effective date of October 24, 2016 (the "NDA"); and

WHEREAS, Seller wishes to sell to Purchaser, and Purchaser wishes to purchase from Seller, all of Debtor's right, title and interest in and to the Transferred Assets pursuant to the provisions of the California Uniform Commercial Code (the "Code").

NOW, THEREFORE, in consideration of the premises and mutual covenants contained herein, and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, Seller and Purchaser agree as follows:

ARTICLE I  
SALE AND PURCHASE

1.1 Agreement to Purchase and Sell. Subject to the terms and conditions of this Agreement, and pursuant to Section 9-610 of the Code, Seller, as a foreclosing creditor in a private sale, agrees to sell, convey, transfer, assign and deliver to Purchaser, and Purchaser agrees to purchase from Seller, all of Debtor's right, title and interest in and to the Transferred Assets. The purchase and sale of the Transferred Assets pursuant to this Agreement may be referred to herein as the "Asset Purchase."

1.2 Purchase Price and Payment of the Purchase Price. The purchase price for the Transferred Assets shall be \$ \_\_\_\_\_ (the "Purchase Price"), which shall be paid in full, in cash, on the Closing Date. As additional consideration, Purchaser shall enter into a Transition Services Agreement with Debtor at the Closing, in substantially the form of Exhibit C attached hereto (the "TSA").

1.3 Closing and Closing Date. Subject to the terms and conditions hereof, the consummation of the Asset Purchase (the "Closing") shall take place at the offices of Seller or such other place as the parties may agree upon in writing, on the date hereof or such other date as the parties may agree upon in writing (the "Closing Date"). If the Closing does not occur on or before Tuesday, November 15, 2016, either Seller or Purchaser may terminate this Agreement effective immediately upon notice in writing to the other party.

1.4 Deliveries at Closing.

At the Closing:

(a) Seller shall deliver to Purchaser, and Seller and Purchaser shall execute, or cause to be executed, a Bill of Sale and Assignment, substantially in the form attached hereto as Exhibit D (the "Bill of Sale");

(b) Purchaser shall pay to Seller, in cash, the full amount of the Purchase Price; and

(c) Purchaser shall enter into the TSA with Debtor.

**Exhibit A to Schedule 1  
to  
Bill of Sale and Assignment**

Patents and Patent Applications

All present and future registered and unregistered patents, including but not limited to the following:

Patent	Application Number	Date
Replaceable cover for membrane carrier	12/806518	8/16/2010
Method for grinding wafers by shaping resilient chuck covering	13/573148	8/27/2012
Devices and methods for measuring wafer characteristics during semiconductor wafer polishing	11/393041	3/29/2006
CMP retaining Ring with soft retaining ring insert	14/295013	6/3/2014
Wafer Carrier with Flexible Pressure Plate	13/243808	9/23/2011
Methods and systems for use in grind shape control adaptation	14/042591	9/30/2013
Systems and methods of processing substrates	13/740101	1/11/2013
Methods and systems for use in grind spindle alignment	14/042600	9/30/2013
Method of grinding wafer stacks to provide uniform residual silicon thickness	14/525115	10/27/2014
Systems and methods of wafer grinding	13/656514	10/19/2012
Back pressure control system for CMP and wafer polishing	11/369700	3/6/2006
Back pressure control system for CMP and wafer polishing	10/452411	5/30/2003
Method of backgrinding wafers while leaving backgrinding tape on a chuck	10/717032	11/18/2003
Polishing pad with built-in optical sensor	10/145332	5/13/2002
Method of backgrinding wafers while leaving backgrinding tape on a chuck	10/315746	12/10/2002
Tool for applying an insert of tape to chucks or wafer carriers used for grinding, polishing, or planarizing wafers	10/259536	9/26/2002

Patent	Registration Number	Date
Chemical Mechanical Polishing Apparatus and Method	6045716	4/4/2000
Method for Chemical Mechanical Polishing	6495463	12/17/2002

Patent	Registration Number	Date
Wafer Support for Chemical Mechanical Planarization	6379235	4/30/2002
Method and Apparatus for Chemical Mechanical Polishing	6361647	3/26/2002
Multi-Pad Apparatus for Chemical Mechanical Planarization	6346036	2/12/2002
Pad Support Apparatus for Chemical Mechanical Planarization	6602121	8/5/2003
Pad Support Method for Chemical Mechanical Planarization	6337133	5/3/2005
Pad Quick Release Device for Chemical Mechanical Polishing	6227956	5/8/2001
Pad Retrieval Apparatus for Chemical Mechanical Planarization	6527621	3/4/2003
Modular Method for Chemical Mechanical Planarization	6855030	2/15/2005
Polishing Chemical Delivery for Small Head Chemical Mechanical Planarization	6514121	2/4/2003
Feature Height Measurement During CMP	6629874	10/7/2003
In SITU Feature Height Measurement	6976901	12/20/2005
Shaping Polishing Pad for Small Head Chemical Mechanical Planarization	6517419	2/11/2003
Multi-Action Chemical Mechanical Planarization Device and Method	6514129	2/4/2003
High Planarity Chemical Mechanical Planarization	6520843	2/18/2003
Pad Quick Release Device for Chemical Mechanical Planarization	6464574	10/15/2002
Spherical Drive Assembly for Chemical Mechanical Planarization	6511368	1/28/2003
Hard Polishing Pad for Chemical Mechanical Planarization	6551179	4/22/2003
Combined Chemical Mechanical Planarization and Cleaning	6692339	2/17/2004
Subaperture Chemical Mechanical Planarization With Polishing Pad Conditioning	6547651	4/15/2003
Subaperture Chemical Mechanical Planarization With Polishing Pad Conditioning	6945856	9/20/2005
A GRINDING APPARATUS HAVING AN EXTENDABLE WHEEL MOUNT	8,133,093	3/13/2012
CONSTANT AUGMENTATION SYSTEM	6,183,341	2/6/2001
SLURRY PUMP CONTROL SYSTEM	6,595,829	7/22/2003



Patent	Registration Number	Date
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	6,485,354	11/26/2002
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	6,739,945	5/25/2004
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	6,696,005	2/24/2004
METHOD OF SPIN ETCHING WAFERS WITH AN ALKALI SOLUTION	6,743,722	6/1/2004
POLISHING PAD WITH OPTICAL SENSOR	6,726,528	4/27/2004
POLISHING PAD SENSOR ASSEMBLY WITH A DAMPING PAD	6,884,150	4/26/2005
SUPPORT FOR THIN WAFERS	6,885,206	4/26/2005
TOOL FOR APPLYING AN INSERT OR TAPE TO CHUCKS OR WAFER CARRIERS USED FOR GRINDING, POLISHING, OR PLANARIZING WAFERS	6,638,389	10/28/2003
A METHOD OF BACKGRINDING WAFERS WHILE LEAVING BACKGRINDING TAPE ON A CHUCK	6,866,564	3/15/2005
ENDPOINT DETECTION SYSTEM FOR WAFER POLISHING	6,695,681	2/24/2004
WAFER CARRIER PIVOT MECHANISM	7,156,946	1/2/2007
BACK PRESSURE CONTROL SYSTEM FOR CMP AND WATER POLISHING	7,008,309	3/7/2006
SLURRY PUMP CONTROL SYSTEM	6,878,037	4/12/2005
RETAINING RING FOR WAFER CARRIERS	6,869,348	3/22/2005
METHOD OF BACKGRINDING WAFERS WHILE LEAVING BACKGRINDING TAPE ON A CHUCK	7,059,942	6/13/2006
DEVICES AND METHODS FOR OPTICAL ENDPOINT DETECTION DURING SEMICONDUCTOR WAFER POLISHING	7,235,154	6/26/2007
ENDPOINT DETECTION SYSTEM FOR WAFER POLISHING	7,052,366	5/30/2006
INDEPENDENT EDGE CONTROL FOR CMP CARRIERS	7,063,604	6/20/2006
CHUCK FOR SUPPORTING WAFERS WITH A FLUID	7,160,808	1/9/2007
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	6,986,701	1/17/2006
CHEMICAL-MECHANICAL PLANARIZATION TOOL FORCE CALIBRATION METHOD AND SYSTEM	7,040,955	5/9/2006
WAFER CARRIER WITH PRESSURIZED MEMBRANE AND RETAINING RING ACTUATOR	7,033,252	4/25/2006
GRINDING PROCESS AND APPARATUS FOR	5,964,646	10/12/1999

Patent	Registration Number	Date
PLANARIZING SAWED WAFERS		
APPARATUS AND METHOD FOR RELIABLY RELEASING WET, THIN WAFERS	6,254,155	7/3/2001
IMPROVED RETAINING RING FOR WAFER CARRIERS	7,063,605	6/20/2006
ROBOT CALIBRATION SYSTEM AND METHOD FOR WAFER HANDLING ROBOTS IN A CMP SYSTEM	7,551,979	6/23/2009
POLISHING PAD WITH BUILT-IN OPTICAL SENSOR	7,083,497	8/1/2006
BACK PRESSURE CONTROL SYSTEM FOR CMP AND WAFER POLISHING	7467990	12/23/2008
WAFER CARRIER WITH PRESSURIZED MEMBRANE AND RETAINING RING ACTUATOR	7,131,892	11/7/2006
ENDPOINT DETECTION SYSTEM FOR WAFER POLISHING	7,195,541	3/27/2007
WAFER CARRIER WITH PRESSURIZED MEMBRANE AND RETAINING RING ACTUATOR	7,238,083	7/3/2007
Devices and Methods for Optical Endpoint Detection During Semiconductor Wafer Polishing	7,549,909	6/23/2009
FLEXIBLE MEMBRANE ASSEMBLY FOR A CMP SYSTEM	7,959,496	6/14/2011
CMP SYSTEM WITH WIRELESS ENDPOINT DETECTION SYSTEM	8,182,312	5/22/2012
ENDPOINT DETECTION SYSTEM FOR WAFER POLISHING	7918712	4/5/2011
CMP RETAINING RING WITH SOFT RETAINING RING INSERT	APPLICATION EXPIRED	
METHOD OF GRINDING WAFER STACKS TO PROVIDE UNIFORM RESIDUAL SILICON THICKNESS	9,082,713	7/14/2015
PROTECTION OF WORK PIECE DURING SURFACE PROCESSING	7,018,268	3/28/2006
METHOD OF PREPARING WHOLE SEMICONDUCTOR WAFER FOR ANALYSIS	6,921,719	7/26/2005
GRINDING APPARATUS AND METHOD	7,118,446	10/10/2006
METHOD, APPARATUS AND SYSTEM FOR USE IN PROCESSING WAFERS	7,249,992	7/31/2007
GRINDING APPARATUS AND METHOD	7458878	12/2/2008

Patent	Registration Number	Date
PRECISION WAFER GRIND ENGINE	8,968,052	3/3/2015
METHOD, APPARATUS AND SYSTEM FOR USE IN PROCESSING WAFERS	8,052,504	11/8/2011
Lap shaping machine with oscillatable point cutter and selectively rotatable or oscillatable lap	4,380,412	4/19/1983
Pad transfer apparatus for chemical mechanical planarization	6,450,860	9/17/2002
Lap milling machine	3,986,433	10/19/1976
Fluid responsive, leverage operated chuck	3,962,832	6/15/1976
Method and apparatus for cleaning grinding work chuck using a vacuum	8,915,771	12/23/2014
CMP retaining ring with soft retaining ring insert	8,740,673	6/3/2014
System and method for in situ monitoring of top wafer thickness in a stack of wafers	8,520,222	8/27/2013
Wafer carrier for film planarization	5,449,316	9/12/1995
Wafer-handling apparatus having a resilient membrane which holds wafer when a vacuum is applied	5,423,716	6/13/1995